

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2854hdd#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 17:13:20)

TOTAL MASS (g) : 0.024068

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001781 | 1000000 | 73997.5546875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009711 | 975000 | 403475.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000239 | 24000 | 9930.04785156 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 124.644950867 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 290.838226318 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.009960 | 1000000 | 413821.25 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000455 | 1000000 | 18919.5527344 | | |
| | | External Plating Total: | | | | 0.000455 | 1000000 | 18919.5527344 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000225 | 1000000 | 9348.37109375 | | |
| Internal Plating Total: | | | | 0.000225 | 1000000 | 9348.37109375 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000845 | 750000 | 35108.328125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000282 | 250000 | 11716.6259766 | | |
| Die Attach Total: | | | | 0.001127 | 1000000 | 46824.953125 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001362 | 130000 | 56588.8085938 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.009013 | 860000 | 374475 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000105 | 10000 | 4362.57324219 | | |
| | | Encapsulation Total: | | | | 0.010480 | 1000000 | 435426.34375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000040 | 1000000 | 1661.93261719 | | |
| | | | | | TOTAL MASS (g) : | 0.024068 | | |